# Exceptionally Low Forward Voltage Trench-based Schottky Rectifier

#### **Features**

- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- These are Pb-Free and Halide-Free Devices

# **Typical Applications**

- Switching Power Supplies including Wireless, Smartphone and Notebook Adapters
- High Frequency and DC–DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting SurfaceTemperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements



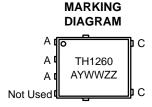
# ON Semiconductor®

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# SCHOTTKY BARRIER RECTIFIERS 12 AMPERES 60 VOLTS







TH1260 = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

#### **ORDERING INFORMATION**

Device	Package	Shipping†
NTS1260MFST1G	SO-8 FL (Pb-Free)	1500 / Tape & Reel
NTS1260MFST3G	SO-8 FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **MAXIMUM RATINGS**

Rating		Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	60	V	
Average Rectified Forward Current (Rated $V_R$ , $T_C = 137^{\circ}C$ )	I <sub>F(AV)</sub>	12	А	
Peak Repetitive Forward Current, (Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 134°C)	I <sub>FRM</sub>	24	А	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	210	А	
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C	
Operating Junction Temperature	TJ	-55 to +150	°C	
Unclamped Inductive Switching Energy (10 mH Inductor, Non-repetitive)	E <sub>AS</sub>	200	mJ	
ESD Rating (Human Body Model)		2		
ESD Rating (Machine Model)		M4		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case, Steady State (Assumes 600 mm <sup>2</sup> 1 oz. copper bond pad, on a FR4 board)	$R_{ heta JC}$	2.0	°C/W

# **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Тур	Max	Unit
Instantaneous Forward Voltage (Note 1)	V <sub>F</sub>			V
(i <sub>F</sub> = 6.0 Amps, T <sub>J</sub> = 25°C)		0.46	_	
$(i_F = 12 \text{ Amps}, T_J = 25^{\circ}\text{C})$		0.53	0.60	
$(i_F = 6.0 \text{ Amps}, T_J = 125^{\circ}\text{C})$		0.39	_	
$(i_F = 12 \text{ Amps}, T_J = 125^{\circ}\text{C})$		0.48	0.58	
Instantaneous Reverse Current (Note 1)	i <sub>R</sub>			
(Rated dc Voltage, T <sub>J</sub> = 25°C)		_	90	μΑ
(Rated dc Voltage, T <sub>J</sub> = 125°C)		15	20	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

# TYPICAL CHARACTERISTICS

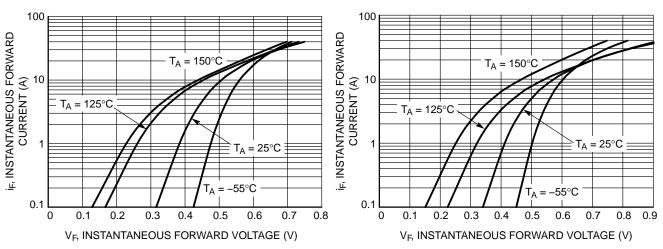


Figure 1. Typical Instantaneous Forward Characteristics

Figure 2. Maximum Instantaneous Forward Characteristics

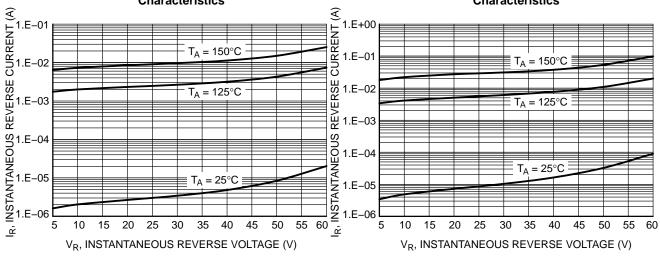


Figure 3. Typical Reverse Characteristics

Figure 4. Maximum Reverse Characteristics

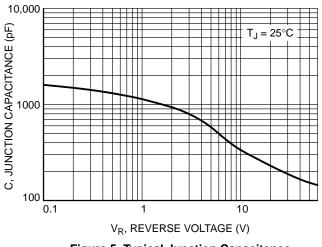


Figure 5. Typical Junction Capacitance

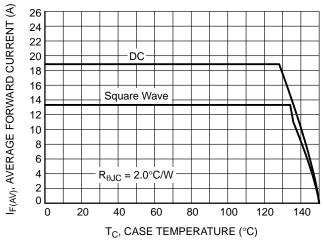
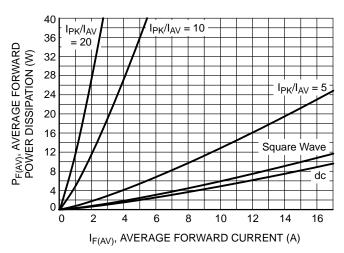
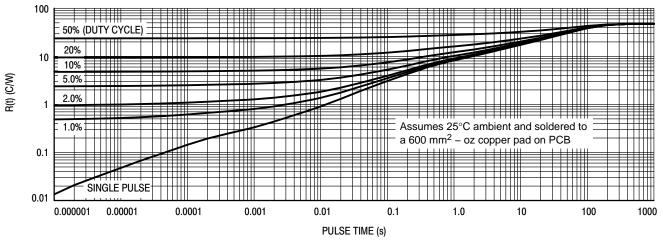


Figure 6. Current Derating per Device

# TYPICAL CHARACTERISTICS



**Figure 7. Forward Power Dissipation** 



**Figure 8. Typical Thermal Characteristics** 

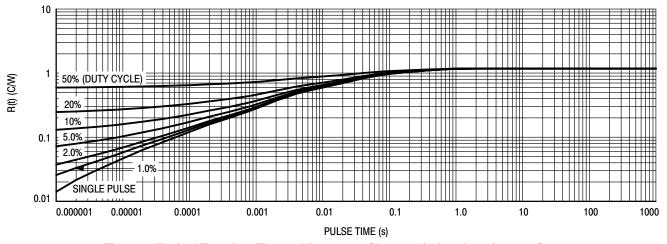
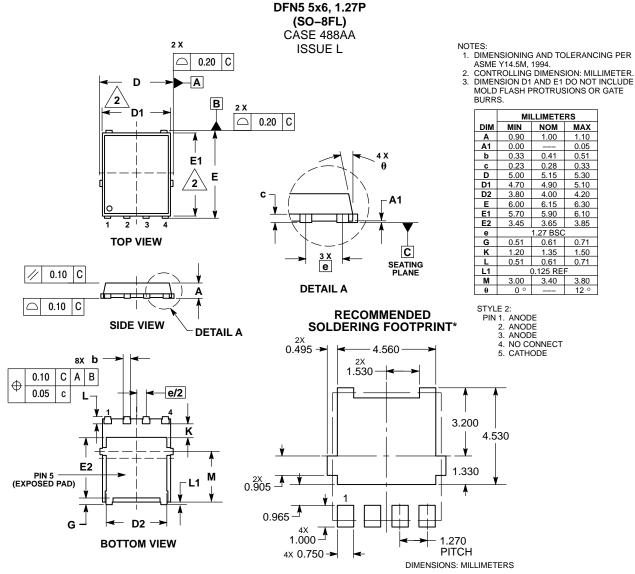


Figure 9. Typical Transient Thermal Response Characteristics, Junction-to-Case

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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